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## U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

10/29/2001  
10/29/2001

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10002779	10/29/2001	438	496	2818	

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10002779	10/29/2001	438		2818	D. VU

\*APPLICANTS: Agarwal Vishnu; Derderian Garo; Sandhu Gurtej; Li Weimin; Visokay  
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\*CONTINUING DATA VERIFIED: Yes DV  
\*PRIORITY CLAIM IS A DIV OF 09/590,795 06/08/2000

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\*PRIORITY CLAIMS VERIFIED: None DV

FOR PUBLICATION <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO
<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	6047-61466	
Title: Methods for forming and integrated circuit structures containing ruthenium and tungsten containing layers		

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner David Helms Supervisor Technology Center 2800 Primary Examiner		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner PREPARED FOR ISSUE WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

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